AUO

CUSTOMER APPROVAL SHEET

Company Name	
MODEL	**A080SN01 V7**
CUSTOMER APPROVED	Title : Name :

☐ **APPROVAL FOR SPECIFICATIONS ONLY (Spec. Ver.＿＿)**

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   Comment :

AUO

Doc. version :	0.0
Total pages :	29

Product Specification

8" COLOR TFT-LCD PANEL

Model Name：	**A080SN01 V7**

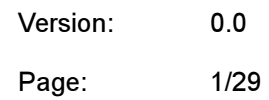|	
Part no:	91.08A07.701
Planned Lifetime:	From 2009/June To 2011/June
Phase-out Control:	From 2011/Jan To 2011/June
EOL Schedule:	2011/June

< ☐ >Preliminary Specification

<　　>Final Specification

Note: The content of this specification is subject to change.

Record of Revision

| Version	Revise Date	Page	Content
0.0	2009/06/04	All	First Draft.

Contents

A. General Information

This product is for portable DVD and digital photo frame application.

NO.	Item	Unit	Specification	Remark
1	Screen Size	inch	8(Diagonal)	
2	Display Resolution	dot	800RGB(W)x600(H)	
3	Overall Dimension	mm	170.1(W) × 132.3(H) × 1.44(D)	Note 1
4	Active Area	mm	162(W)x121.5(H)	
5	Pixel Pitch	mm	0.2025(W)x0.2025(H)	
6	Color Configuration	--	R. G. B. Stripe	Note 2
7	Color Depth	--	16.7M Colors	Note 3
8	NTSC Ratio	%	50	
9	Display Mode	--	Normally White	
10	Panel surface Treatment	--	Anti-Glare, 3H	
11	Weight	g	65	
12	Panel Power Consumption	mW	230	Note 4
13	Backlight Power Consumption	W	xx	
	Viewing direction		6 o'clock (gray inversion)	

Note 1: Not include blacklight cable and FPC. Refer next page to get further information.

Note 2: Below figure shows dot stripe arrangement.
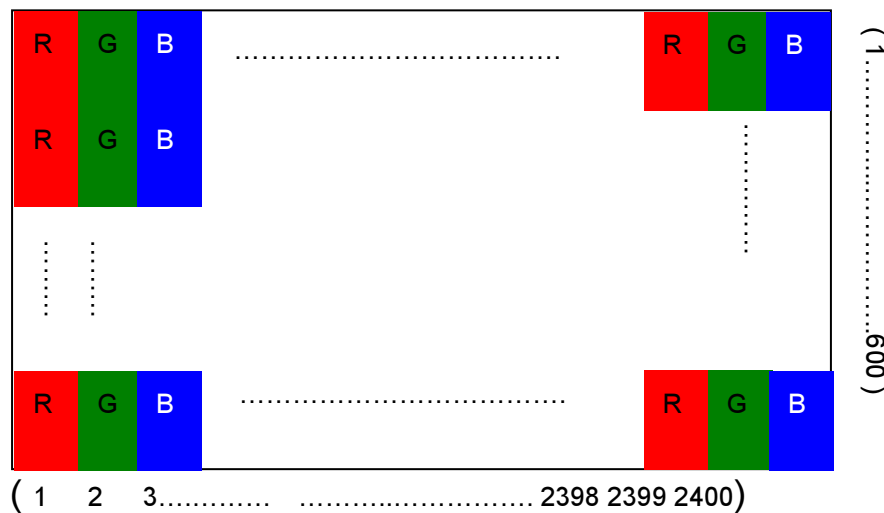
Note 3: The full color display depends on 24-bit data signal (pin 4~27).

Note 4: Please refer to Electrical Characteristics chapter.

B. Outline Dimension

1. TFT-LCD Module – Front View

1.General tolerance ±0.3mm.
2.The bending radius of FPC should be larger than 0.6mm
3.FPC connector:XF2M-6015-1AH BY omz

DETAIL C SCALE 2/1

DETAIL B SCALE 2/1

DETAIL A SCALE 2/1

PITCH=0.5±0.03

0.5*(60−1)=29.5±0.05

30.5±0.1

0.35±0.03

0.5±0.1

0.3±0.2

0.5±0.03

PIN60

PIN1

(0.07)

3.51

1.7

0.22

0.22

1

SEE DETAIL B

SEE DETAIL C

SEE DETAIL A

170.1
166.7 (CF)
165.6 (Upper Polarizer)
162(Active Area)
(83.2)
(0.4)
2.2

132.3
126.5 (CF)
125.1 (Upper Polarizer)
121.5 (Active Area)
(69.05)
5.8
(6.5)
8.3

110.81 ±0.5
126.06 ±0.5

SCALE 1/2

2. TFT-LCD Module – Rear View

164.2(Bottom Polarizer)

125.1(Bottom Polarizer)

(1.1)

(7.2)

61.45

5±0.5
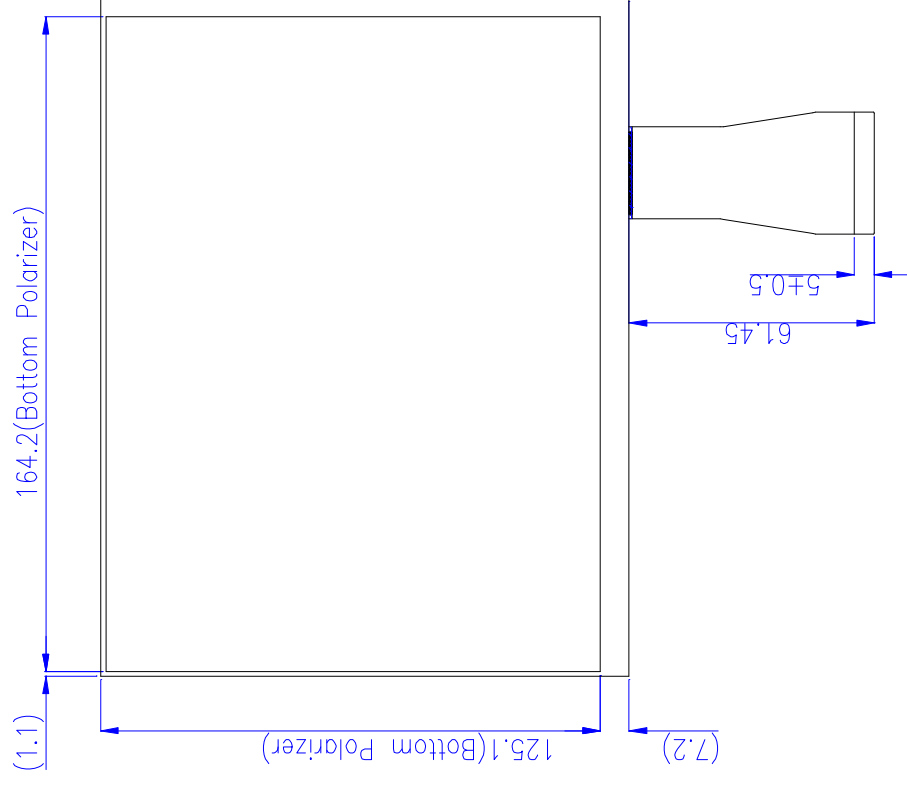
C. Electrical Specifications
1. TFT LCD Panel Pin Assignment
Recommended connector : XF2M-6015-1AH

Pin no	Symbol	I/O	Description	Remark
1	AGND	P	Analog Ground	
2	AVDD	P	Analog Power	
3	VCC	P	Digital Power	
4	R0	I	Data input (LSB)	
5	R1	I	Data input	
6	R2	I	Data input	
7	R3	I	Data input	
8	R4	I	Data input	
9	R5	I	Data input	
10	R6	I	Data input	
11	R7	I	Data input (MSB)	
12	G0	I	Data input (LSB)	
13	G1	I	Data input	
14	G2	I	Data input	
15	G3	I	Data input	
16	G4	I	Data input	
17	G5	I	Data input	
18	G6	I	Data input	
19	G7	I	Data input (MSB)	
20	B0	I	Data input (LSB)	
21	B1	I	Data input	
22	B2	I	Data input	
23	B3	I	Data input	
24	B4	I	Data input	
25	B5	I	Data input	
26	B6	I	Data input	
27	B7	I	Data input (MSB)	
28	DCLK	I	Clock input	
29	DE	I	Data enable signal	
30	HSYNC	I	Horizontal sync input. Negative polarity	
31	VSYNC	I	Vertical sync input. Negative polarity	
32	SCL	I	Serial communication clock input	
33	SDA	I	Serial communication data input	
34	CSB	I	Serial communication chip select	

35	NC	-	For test, do not connect (Please leave it open)	
36	VCC	P	Digital Power	
37	NC	-	For test, do not connect (Please leave it open)	
38	GND	P	Digital ground	
39	AGND	P	Analog ground	
40	AVDD	P	Analog Power	
41	VCOMin	I	For external VCOM DC input (Optional)	
42	DITH	I/O	Dithering setting DITH = "L" 6bit resolution(LSB last 2 bits of input data turncated) DITH = "H" 8bit resolution(Default setting)	
43	NC	-	For test, do not connect (Please leave it open)	
44	VCOM	O	connect a capacitor	
45	V10	P	Gamma correction voltage reference	
46	V9	P	Gamma correction voltage reference	
47	V8	P	Gamma correction voltage reference	
48	V7	P	Gamma correction voltage reference	
49	V6	P	Gamma correction voltage reference	
50	V5	P	Gamma correction voltage reference	
51	V4	P	Gamma correction voltage reference	
52	V3	P	Gamma correction voltage reference	
53	V2	P	Gamma correction voltage reference	
54	V1	P	Gamma correction voltage reference	
55	NC	-	For test, do not connect (Please leave it open)	
56	VGH	P	Positive power for TFT	
57	VCC	P	Digital Power	
58	VGL	P	Negative power for TFT	
59	GND	P	Digital Ground	
60	NC	-	NC PIN	

I: Input; P: Power; G: Ground; C: Capacitor

2. Backlight driving section

No.	Symbol	I/O	Description	Remark
1	VLED	I	LED power supply	--
2	GNDLED	-	LED ground	--

3. Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit	Remark
Power voltage	V_{CC}	GND=0	-0.5	5	V	
	AV_{DD}	AGND=0	-0.5	15	V	
	V_{GH}	GND=0	-0.3	42	V	
	V_{GL}		-20	0.3	V	
	$V_{GH}-V_{GL}$		-	40	V	
Input signal voltage	V_I		-0.3	V_{CC}+0.3	V	Note 1
	VCOM		0	6.5	V	
Operating temperature	Topa		-10	60	℃	
Storage temperature	Tstg		-20	70	℃	

Note 1: HS , VS , DE, Digital Data.

Note 2: Functional operation should be restricted under ambient temperature (25℃).

Note 3: Maximum ratings are those values beyond which damages to the device may occur. Functional

operation should be restricted to the limits in the Electrical Characteristics chapter.
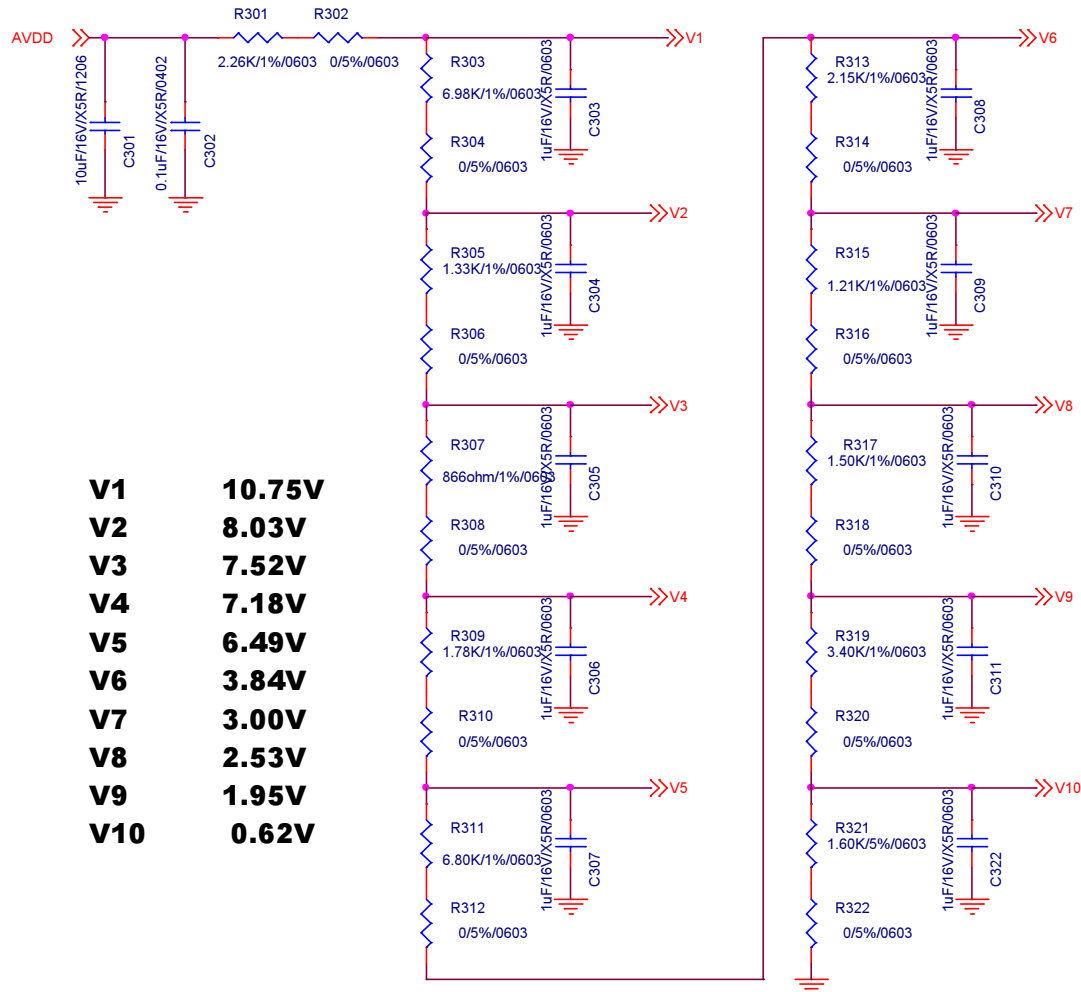
4. Electrical DC Characteristics

a. (VCC = +3.3V, AVDD=11.68V, AGND=GND=0V, TOPR = -10°C to +60°C)

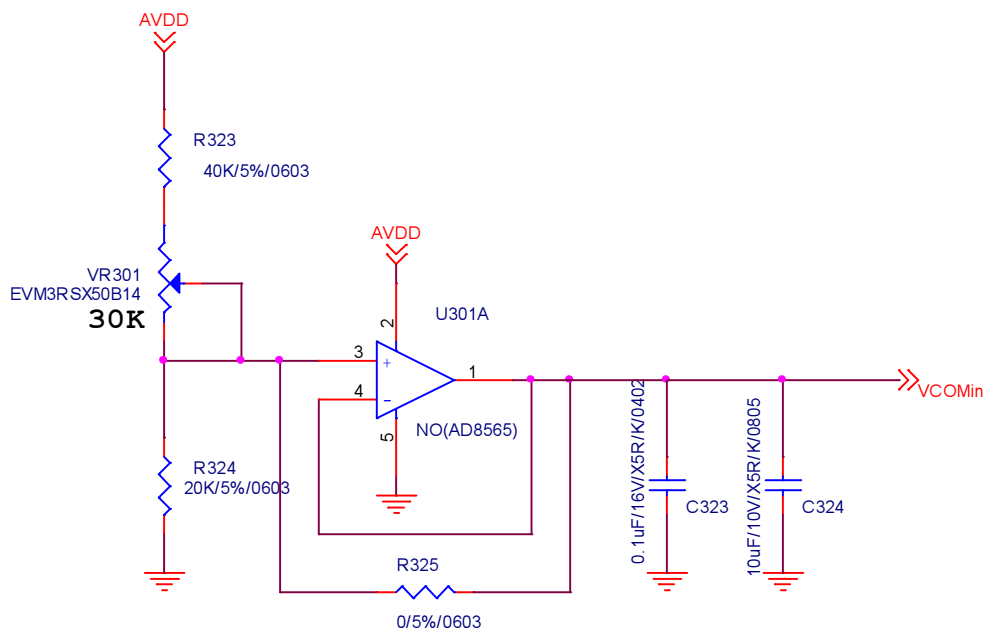| Item		Symbol	Min.	Typ.	Max.	Unit	Remark
Power supply		V_{CC}	3.0	3.3	3.6	V	
		AV_{DD}	11	11.68	12	V	
		V_{GH}	14	15	16	V	
		V_{GL}	-7.5	-6.75	-5	V	
Power Consumption		P	-	230	260	mW	Black Pattern
VCOM		V_{CDC}	3.4	3.6	3.8	V	DC component
Input signal	H Level	V_{IH}	0.7 V_{CC}	-	V_{CC}	V	Note 1
	L Level	V_{IL}	0	-	0.3 V_{CC}	V	
Input level of V1~V5		Vx	0.4*AVDD	-	AVDD-0.5	V	Positive gamma correction voltage Note 2
Input level of V6~V10		Vx	0.5	-	0.6*AVDD	V	Negative gamma correction voltage Note 2

Note 1: HS , VS , DE, Digital Data
Note 2 : AGND <V10<V9V<8V7<V6<V5<V4<V3<V2<V1<AVDD

b. Gamma voltage suggested circuit is as follows

AVDD

R301 2.26K/1%/0603
R302 0/5%/0603

C301 10uF/16V/X5R/1206
C302 0.1uF/16V/X5R/0402

R303 6.98K/1%/0603
R304 0/5%/0603
C303 1uF/16V/X5R/0603 → V1

R305 1.33K/1%/0603
R306 0/5%/0603
C304 1uF/16V/X5R/0603 → V2

R307 866ohm/1%/0603
R308 0/5%/0603
C305 1uF/16V/X5R/0603 → V3

R309 1.78K/1%/0603
R310 0/5%/0603
C306 1uF/16V/X5R/0603 → V4

R311 6.80K/1%/0603
R312 0/5%/0603
C307 1uF/16V/X5R/0603 → V5

R313 2.15K/1%/0603
R314 0/5%/0603
C308 1uF/16V/X5R/0603 → V6

R315 1.21K/1%/0603
R316 0/5%/0603
C309 1uF/16V/X5R/0603 → V7

R317 1.50K/1%/0603
R318 0/5%/0603
C310 1uF/16V/X5R/0603 → V8

R319 3.40K/1%/0603
R320 0/5%/0603
C311 1uF/16V/X5R/0603 → V9

R321 1.60K/5%/0603
R322 0/5%/0603
C322 1uF/16V/X5R/0603 → V10

V1	10.75V
V2	8.03V
V3	7.52V
V4	7.18V
V5	6.49V
V6	3.84V
V7	3.00V
V8	2.53V
V9	1.95V
V10	0.62V

c.Vcom buffer suggested circuit is as follows

AVDD

R323 40K/5%/0603

VR301 EVM3RSX50B14 30K

AVDD

U301A NO(AD8565)

R324 20K/5%/0603

R325 0/5%/0603

C323 0.1uF/16V/X5R/K/0402
C324 10uF/10V/X5R/K/0805

→ VCOMin

d. Current Consumption (AGND=GND=0V)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Input current for VCC	I_{VCC}	V_{CC}=3.3V	-	11	14	mA	Black Pattern
Inpur current for AVDD	I_{AVDD}	AVDD=11.7V	-	16	20	mA	Black Pattern
Input current for VGH	I_{VGH}	VGH=15V	-	0.16	0.2	mA	Black Pattern
Inpur current for VGL	I_{VGL}	VGL=-6.75V	-	0.16	0.2	mA	Black Pattern

e. Backlight Driving Conditions

This is panel only module without BLU structure.

5. Electrical AC Characteristics

a. Signal AC Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit.	Remark
Clock High time	T_{WCL}	8	-	-	ns	
Clock Low time	T_{WCH}	8	-	-	ns	
Hsync setup time	T_{HSU}	5	-	-	ns	
Hsync hold time	T_{HHD}	10	-	-	ns	
Vsync setup time	T_{VSU}	0	-	-	ns	
Vsync hold time	T_{VHD}	2	-	-	ns	
Data setup time	T_{DSU}	5	-	-	ns	
Data hold time	T_{DHD}	10	-	-	ns	
Data enable set-up time	T_{ESU}	4	-	-	ns	
Data enable hold time	T_{EHD}	2	-	-	ns	
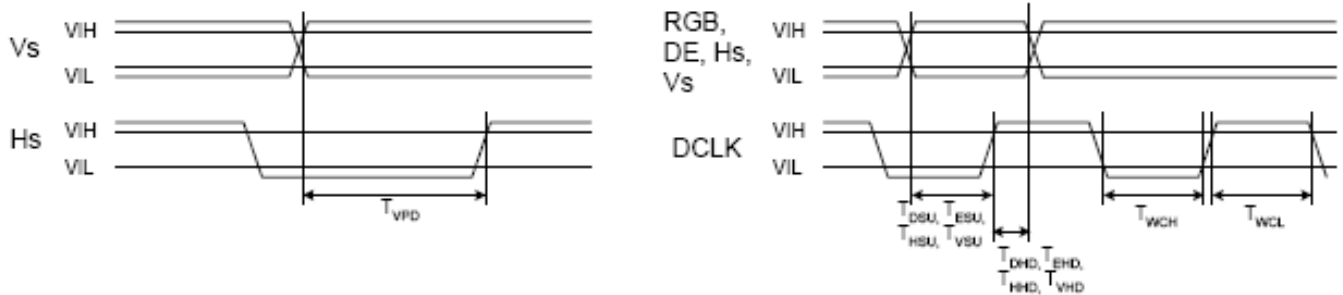
6. RGB Parallel Input Timing

a. Horizontal timing

Parameter	Symbol	Min.	Typ.	Max.	Unit.	Remark
DCLK frequency	F_{DCLK}	25	40	45	MHz	
DCLK period	T_{DCLK}	22	25	40	ns	
Hsync period (= T_{HD} + T_{HBL})	T_H	986	1056	1183	DCLK	
Active Area	T_{HD}	-	800	-	DCLK	

Horizontal blanking (= T_{HF} + T_{HE})	T_{HBL}	186	256	383	DCLK	
Hsync front porch	T_{HF}	-	40	-	DCLK	
Delay from Hsync to 1st data input (= T_{HW} + T_{HB})	T_{HE}	88	216	343	DCLK	Function of HDL[7..0] settings
Hsync pulse width	T_{HW}	1	128	136	DCLK	
Hsync back porch	T_{HB}	10	88	342	DCLK	
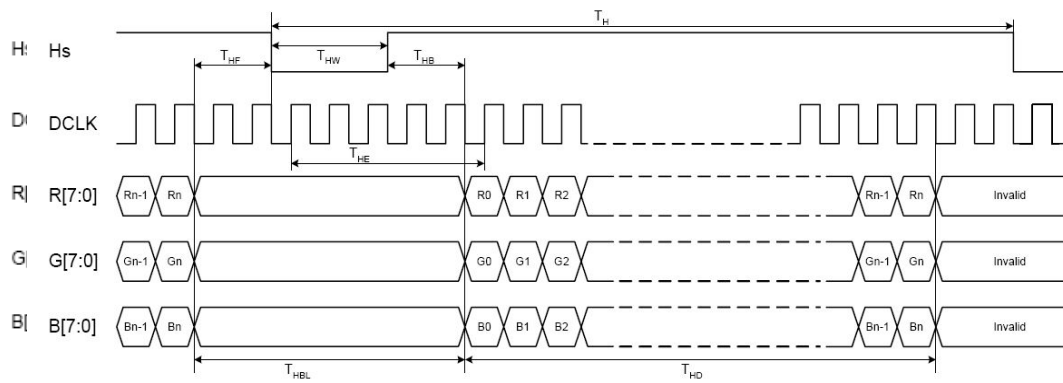
Horizontal input timing (HV mode)
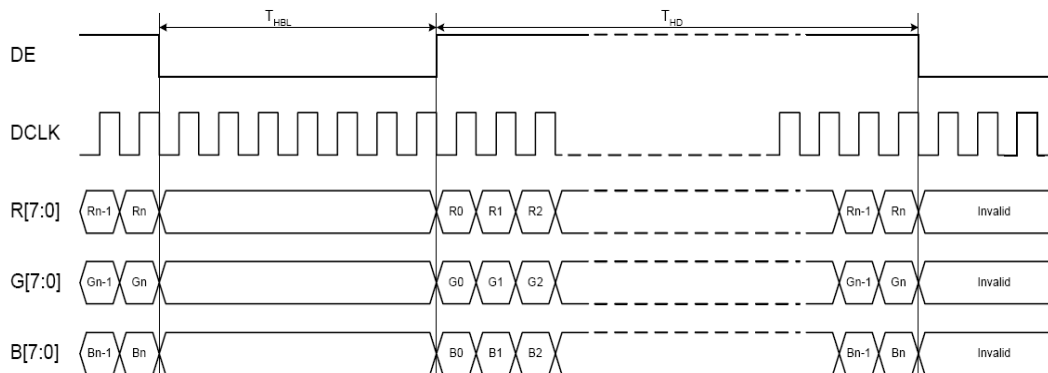
Horizontal input timing (DE mode)

b. Vertical timing

Parameter	Symbol	Min.	Typ.	Max.	Unit.	Remark
Vsync period (= T_{VD} + T_{VBL})	T_V	620	628	635	Th	
Active lines	T_{VD}	-	600	-		
Vertical blanking (= T_{VF} + T_{VE})	T_{VBL}	20	28	35	Th	
Vsync front porch	T_{VF}	-	1	-	Th	
GD start pulse delay	T_{VE}	19	27	34	HS	Function of VDL[3..0] settings
Vsync pulse width	T_{VW}	1	3	16	Th	
Hsync/Vsync phase shift	T_{VPD}	2	320	-	DCLK	
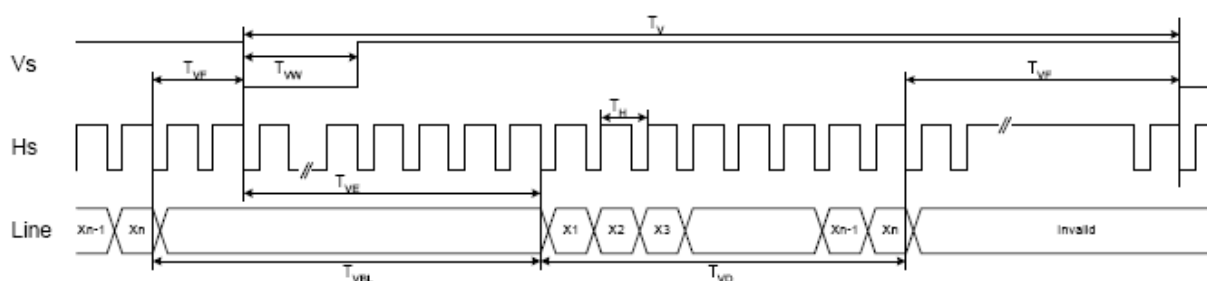
Vertical timing (HV mode)
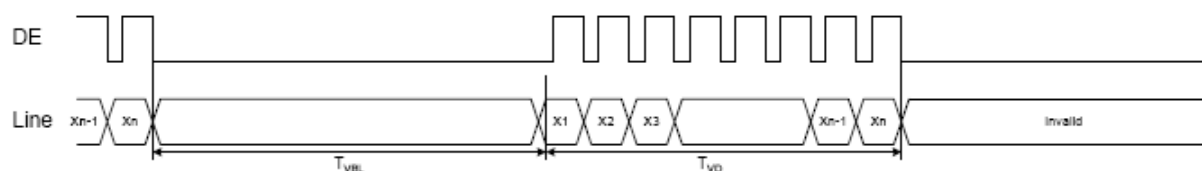
Vertical timing (DE mode)

7. Serial Interface Characteristics

a. Serial Control Interface AC Characteristic

| Parameter	Symbol	Min.	Typ.	Max.	Unit.	Remark
Serial data setup time	T_{IST}	120	-	-	ns	
Serial data hold time	T_{IHD}	120	-	-	ns	
CSB setup time	T_{CST}	120	-	-	ns	
CSB hold time	T_{CHD}	120	-	-	ns	
Serial clock high/low	T_{SSW}	120	-	-	ns	
Serial clock	T_{SCK}	320	-	-	ns	
Delay from CSB to VSYNC	T_{CV}	120	-	-	us	
Chip select distinguish	T_{CD}	120	-	-	us	
Serial data output delay	T_{ID}	-	-	60	ns	CL=20pF
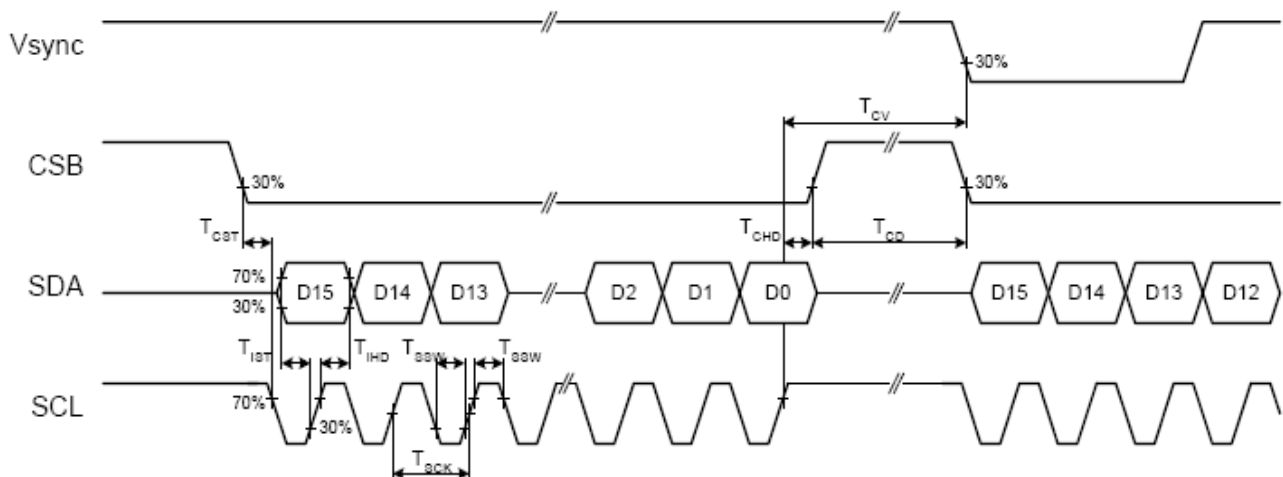
AC serial interface write mode timings
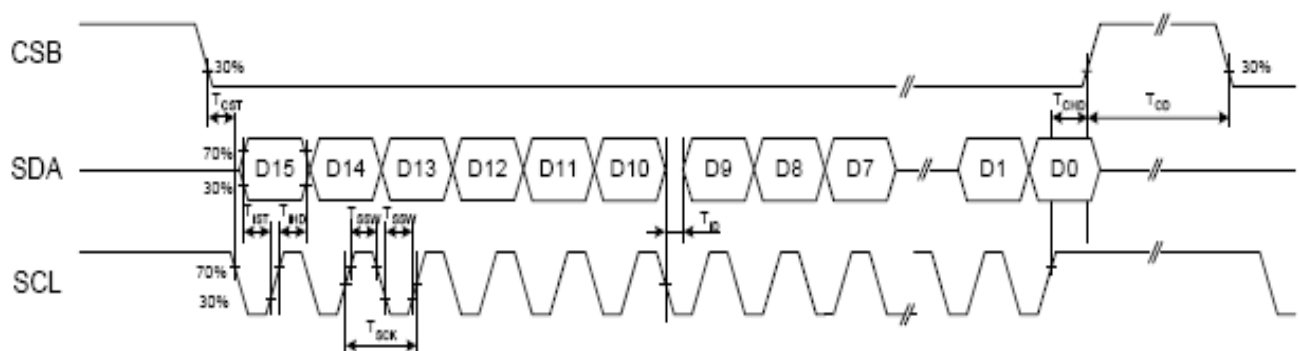
AC serial interface read mode timings

b. Register Bank

There is a total of 6 registers each containing several parameters. For a detailed description of the parameters refer to register table. The serial register has read/write function. D[15:12] are the register address, D[11] defines the read or write mode and D[10:0] are the data.
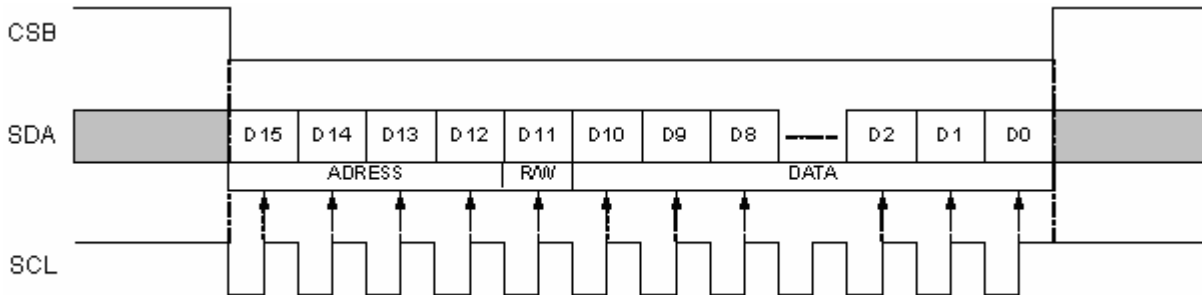
Serial interface write/read sequence

1. At power-on, the default values specified for each parameter are taken.

2. If less than 16-bit data are read during the CS low time period, the data is cancelled.

   a. The write operation is cancelled.

   b. The read operation is interrupt.

3. If more than 16-bit data are read during the CS low time period, the last 16 bits are kept.

   a. Address & R/W are always defined form CSB falling edge.

   b. The write operation load last 11 bit data before CSB rising edge.

   c. The read operation is "D0" is output to SDA until CSB rising edge.

4. All items are set at the falling edge of the vertical sync, except R0[1:0].

5. When GRB is activated through the serial interface, all registers are cleared, except the GRB value.

6. Register R/W setting: D11 = "L" → write mode; D11 = "H" → read mode.

7. The register setting values are valid when VCC already goes to high and after VSYNC starts.

8. It is suggested that VSYNC, HSYNC, DCLK always exists in the same time. But if HSYNC, DCLK stops, only VSYNC operating, the register setting is still valid.

9. If the chip goes to standby mode, the register value will still keep. MCU can wake up the chip only by changing standby mode value from low to high.

10. The register setting values are rewritten by the influence of static electricity, a noise, etc. to unsuitable value, incorrect operating may occur. It is suggested that the SPI interface will setup as frequently as possible.

c. Register Table (Default Value)

➢ When GRB is low, all registers reset to default values, which are in the brackets.

➢ Serial commands are executed at next VSYNC signal.

Reg	ADDRESS				R/W	DATA										
No.	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
R0	0	0	0	0	0	(01)		(01)		(1)	(0)	(1)	(1)	(0)	GRB (1)	STB (1)
R1	0	0	0	1	0	×	(0)	(1)	(01)		(2Fh)					
R2	0	0	1	0	0	×	×	×	HDL (80h)							
R3	0	0	1	1	0	×	×	(0)	(0)	(0)	(0)	(0)	VDL (1000)			
R4	0	1	0	0	0	×	×	(0)	(0)	(0)	(0)	(1)	(1111)			
R6	0	1	1	0	0	×	(0)	EnGB12 (1)	EnGB11 (1)	EnGB10 (1)	(0)	(0)	EnGB5 (1)	EnGB4 (1)	EnGB3 (1)	(0)

"x" => reserved bit, please set to '0'.

<Note>：Sending serial commands periodically is recommended to improve ESD protection ability.

d. Register Description

➢ When GRB is low, all registers reset to default values, which are in the brackets.

➢ Serial commands are executed at next VSYNC signal.

1.. R0 setting

Address	Bit	Description		Default
0000	[10..0]	Bits 10-9	AUO Internal Use	01
		Bits7-8	AUO Internal Use	01
		Bit6	AUO Internal Use	1
		Bit5	AUO Internal Use	0
		Bit4	AUO Internal Use	1
		Bit3	AUO Internal Use	1
		Bit2	AUO Internal Use	0
		Bit1 (GRB)	Global reset.	1
		Bit0 (STB)	Standby mode setting.	1

Bit1	GRB function
0	The controller is reset. Reset all registers to default value.
1	Normal operation. **(default)**

Bit0	STB function

| 0 | T-CON, source driver and DC-DCs converters are off. All outputs are set to GND. |
| 1 | Normal operation. **(default)** |

2. R2 setting

Address	Bit	Description		Default
0010	[7..0]	Bit7-0(HDL)	Horizontal start pulse adjustment function	80H

Bit7-0	HDL function
00h	T_{HE} = T_{HEtyp} - 128 CLK period.
80h	T_{HE} = T_{HEtyp}. **(default)**
FFh	T_{HE} = T_{HEtyp} + 127 CLK period.

3. R3 setting

Address	Bit	Description		Default
0011	[8..0]	Bit8	AUO Internal Use	0
		Bit7	AUO Internal Use	0
		Bit6	AUO Internal Use	0
		Bit5	AUO Internal Use	0
		Bit4	AUO Internal Use	0
		Bit3-0(VDL)	Vertical start pulse adjustment function	1000

Bit3-0	VDL function
0000	T_{VE} = T_{VEtyp} − 8 Hs period.
0001	T_{VE} = T_{VEtyp} − 7 Hs period.
0010	T_{VE} = T_{VEtyp} − 6 Hs period.
0011	T_{VE} = T_{VEtyp} − 5 Hs period.
0100	T_{VE} = T_{VEtyp} − 4 Hs period.
0101	T_{VE} = T_{VEtyp} − 3 Hs period.
0110	T_{VE} = T_{VEtyp} − 2 Hs period.
0111	T_{VE} = T_{VEtyp} − 1 Hs period.
1000	T_{VE} = $T_{VEtyp.}$ (default)
1001	T_{VE} = T_{VEtyp} − 1 Hs period.
1010	T_{VE} = T_{VEtyp} − 2 Hs period.
1011	T_{VE} = T_{VEtyp} − 3 Hs period.
1100	T_{VE} = T_{VEtyp} − 4 Hs period.

1101	T_{VE} = T_{VEtyp} − 5 Hs period.
1110	T_{VE} = T_{VEtyp} − 6 Hs period.
1111	T_{VE} = T_{VEtyp} − 7 Hs period.

4. R6 setting

Address	Bit	Description		Default
0110	[9..0]	Bits9	AUO Internal Use	0
		Bits8(EnGB12)	Gamma buffer Enable for V9	1
		Bits7(EnGB11)	Gamma buffer Enable for V8	1
		Bits6(EnGB10)	Gamma buffer Enable for V7	1
		Bits5	AUO Internal Use	0
		Bits4	AUO Internal Use	0
		Bits3(EnGB5)	Gamma buffer Enable for V4	1
		Bits2(EnGB4)	Gamma buffer Enable for V3	1
		Bits1(EnGB3)	Gamma buffer Enable for V2	1
		Bits0	AUO Internal Use	0

Bitx	EnGBx function
0	Gamma buffer for VX is disabled (High Z).
1	Gamma buffer is enabled. VX must be connected externally.

"x" => reserved bit, please set to '0'.

<Note>：Sending serial commands periodically is recommended to improve ESD protection ability.
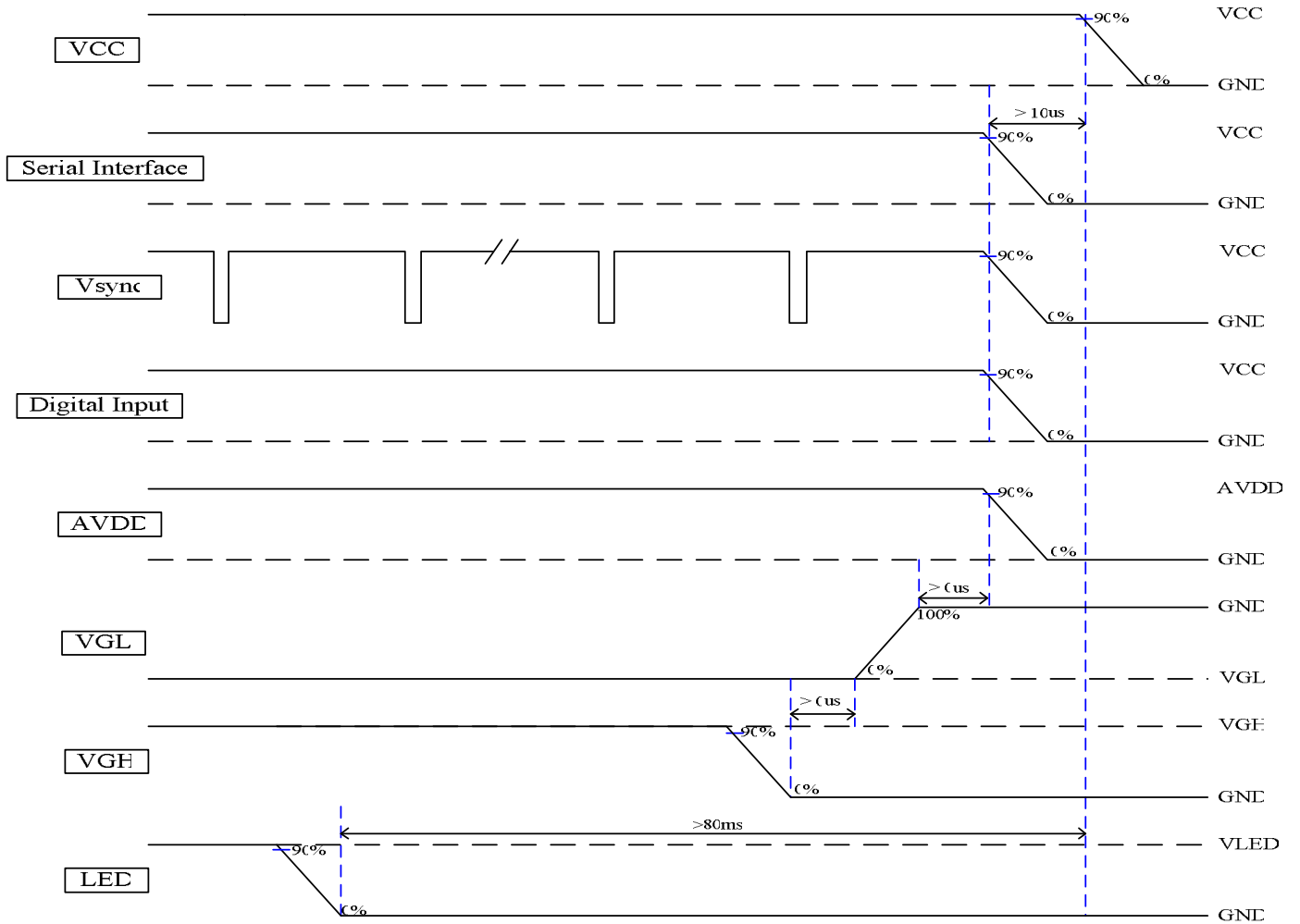
8. Power On/Off Characteristics

a. Recommended Power On Register Setting

Reg	ADDRESS				R/W	DATA										
No.	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
R0	0	0	0	0	0	10		01		1	0	1	0	0	1	1
R1	0	0	0	1	0	0	01		01		2Fh					
R2	0	0	1	0	0	0	0	0	80h							
R3	0	0	1	1	0	0	0	0	0	0	0	0	1000			
R4	0	1	0	0	0	0	0	1	1	00		1	1111			
R6	0	1	1	0	0	0	0	1	1	1	0	0	1	1	1	0

b. Recommended Power On Sequence
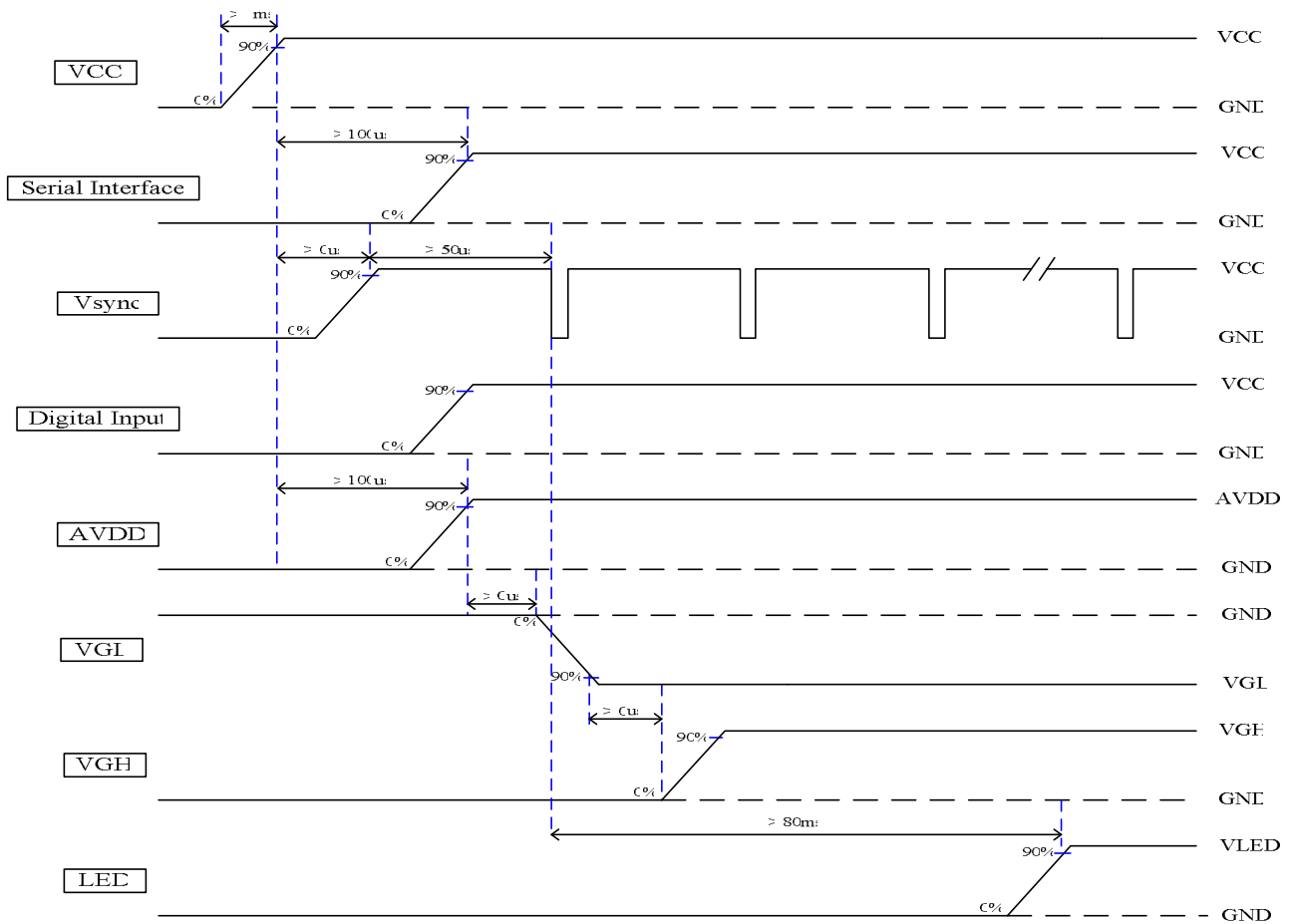
c. Power Off Sequence

D. Optical Specification

All optical specification is measured under typical condition (Note 1, 2)

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response Time					4	8		
Rise		Tr	θ=0°	--			ms	Note 1
Fall		Tf		--	16	32	ms	
Contrast ratio		CR	At optimized viewing angle	400	500	--		Note 2
Viewing Angle	Top			50	60			
	Bottom		CR≧10	50	65		deg.	Note 3
	Left			60	70			
	Right			60	70			
Transmission		Y_L	θ=0°	3.8	4.0	--	%	

Note 1: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white"(falling time) and from "white" to "black"(rising time), respectively.

The response time is defined as the time interval between the 10% and 90% of amplitudes. Refer to figure as below.
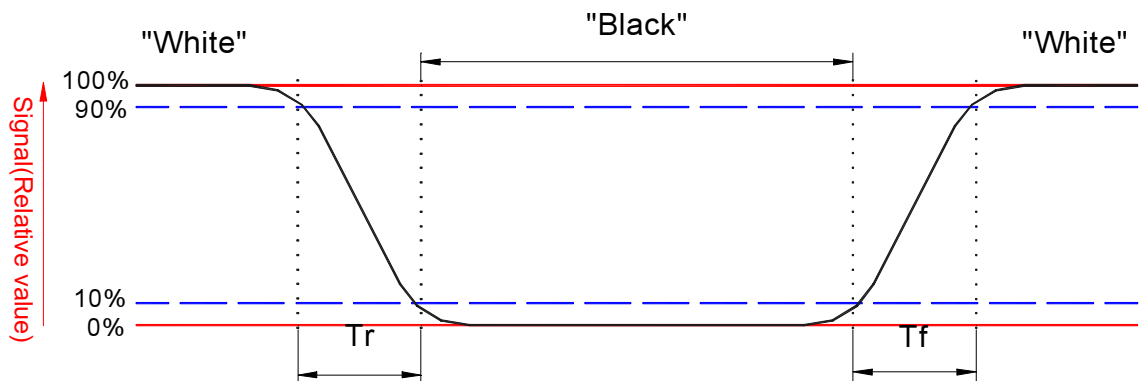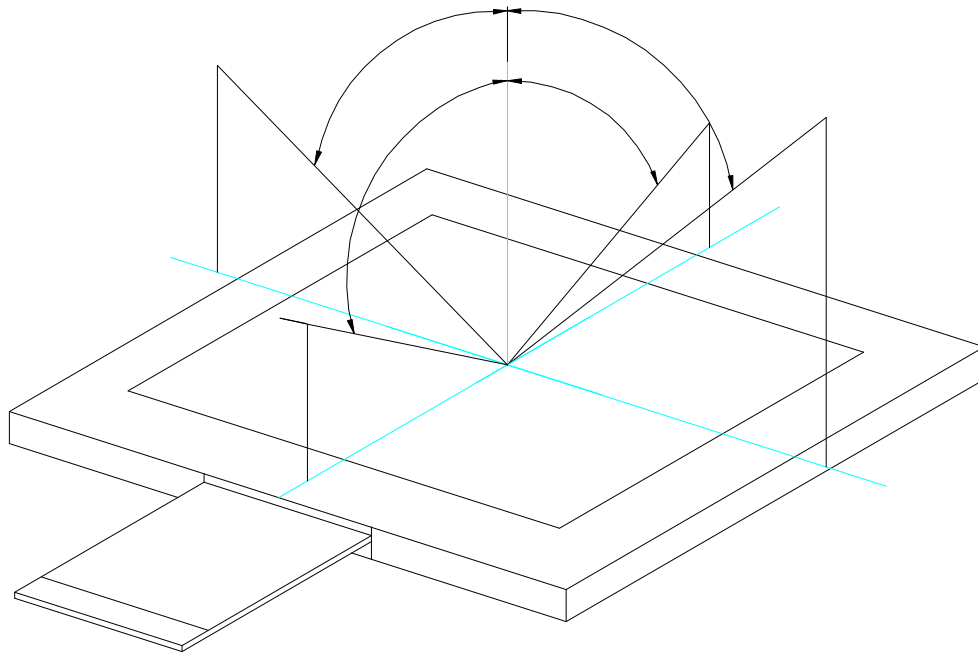

Note 2.Definition of contrast ratio:

Contrast ratio is calculated with the following formula.

$$\text{Contrast ratio (CR)} = \frac{\text{Photo detector output when LCD is at "White" status}}{\text{Photo detector output when LCD is at "Black" status}}$$

Note 3. Definition of viewing angle, θ, Refer to figure as below.

E. Reliability Test Items

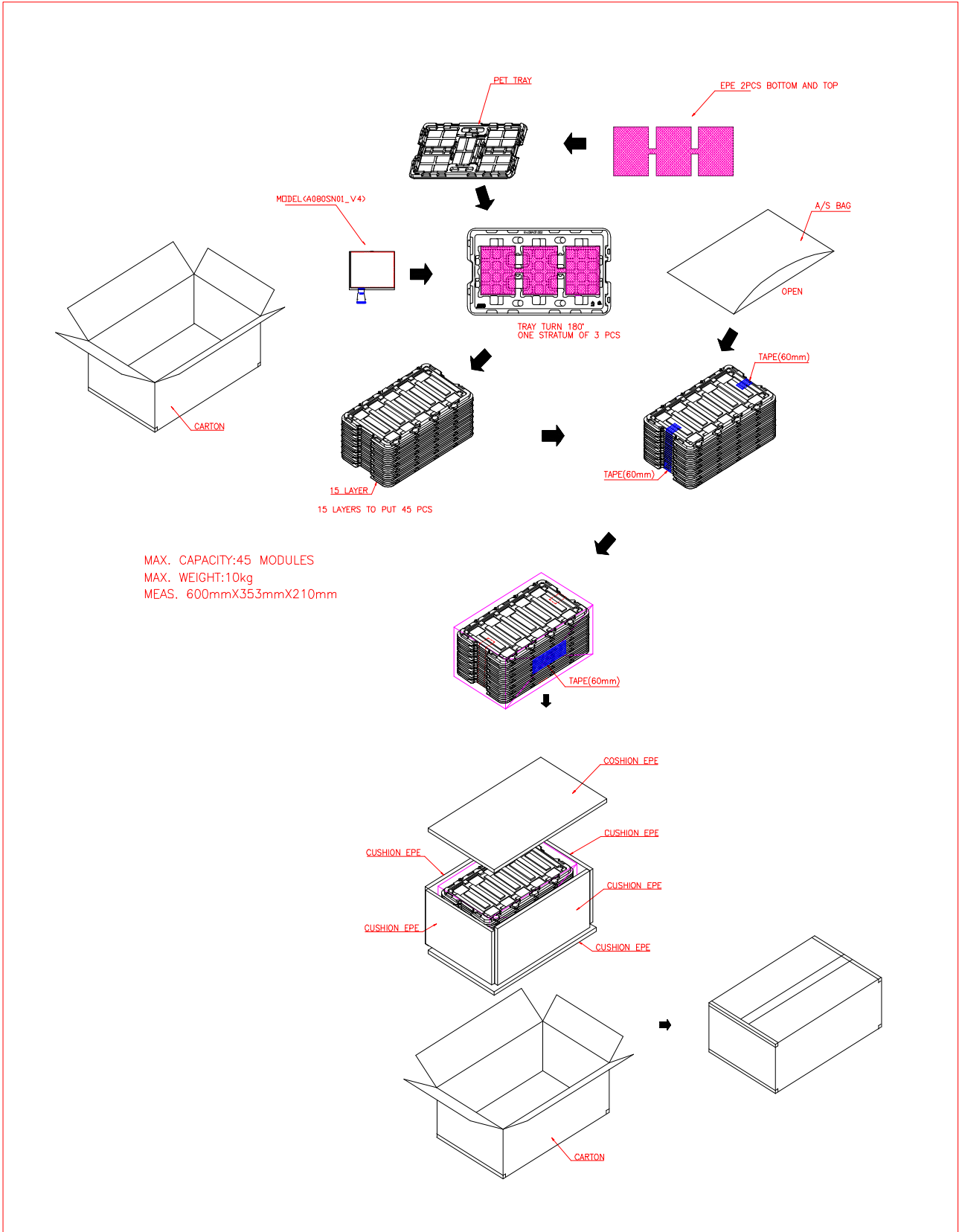| No.	Test items	Conditions		Remark
1	High Temperature Storage	Ta= 70□	240Hrs	
2	Low Temperature Storage	Ta= -20□	240Hrs	
3	High Ttemperature Operation	Tp= 60□	240Hrs	
4	Low Temperature Operation	Ta= -10□	240Hrs	
5	High Temperature & High Humidity	Tp= 50□. 80% RH	240Hrs	Operation
6	Heat Shock	-10□~60□, 50 cycle, 1Hrs/cycle		Non-operation
7	Vibration (With Carton)	Random vibration: $0.015G^2$/Hz from 5~200Hz –6dB/Octave from 200~500Hz		IEC 68-34
8	Drop (With Carton)	Height: 60cm 1 corner, 3 edges, 6 surfaces		

Note 1: Ta: Ambient Temperature. Tp: Panel Surface Temperature

Note 2: In the standard conditions, there is not display function NG issue occurred. All the cosmetic specification is judged before the reliability stress.

Note 3: All the cosmetic specification is judged before the reliability stress.

F. Packing and Marking

1. Packing Form

PET TRAY

EPE 2PCS BOTTOM AND TOP

MODEL(A080SN01_V4)

A/S BAG

OPEN

TRAY TURN 180°
ONE STRATUM OF 3 PCS

TAPE(60mm)

CARTON

TAPE(60mm)

15 LAYER

15 LAYERS TO PUT 45 PCS

MAX. CAPACITY:45 MODULES
MAX. WEIGHT:10kg
MEAS. 600mmX353mmX210mm

TAPE(60mm)

COSHION EPE

CUSHION EPE

CUSHION EPE

CUSHION EPE

CUSHION EPE

CUSHION EPE

CARTON

2. Module/Panel Label Information

      The module/panel (collectively called as the "Product") will be attached with a label of Shipping Number which represents the identification of the Product at a specific location.   Refer to the Product outline drawing for detailed location and size of the label.   The label is composed of a 22-digit serial number and printed with code 39/128 with the following definition:

```
ABCDEFGHIJKLMNOPQRSTUV
        └─For internal system usage and production serial numbers.
      └─AUO Module or Panel factory code, represents the final production factory to complete the Product
   └─Product version code, ranging from 0~9 or A~Z (for Version after 9)
 └─Week Code, the production week when the product is finished at its production process
```

3. Carton Label Information

      The packing carton will be attached with a carton label where packing Q'ty, AUO Model Name, AUO Part Number, Customer Part Number (Optional) and a series of Carton Number in 13 or 14 digits are printed.   The Carton Number is apparing in the following format:

```
ABC-DEFG-HIJK-LMN
        └─ DEFG appear after first "-" represents the packing date of the carton
      └─Date from 01 to 31
    └─ Month, ranging from 1~9, A~C. A for Oct, B for Nov and C for Dec.
  └─A.D. year, ranging from 1~9 and 0.  The single digit code reprents the last number of the year
```
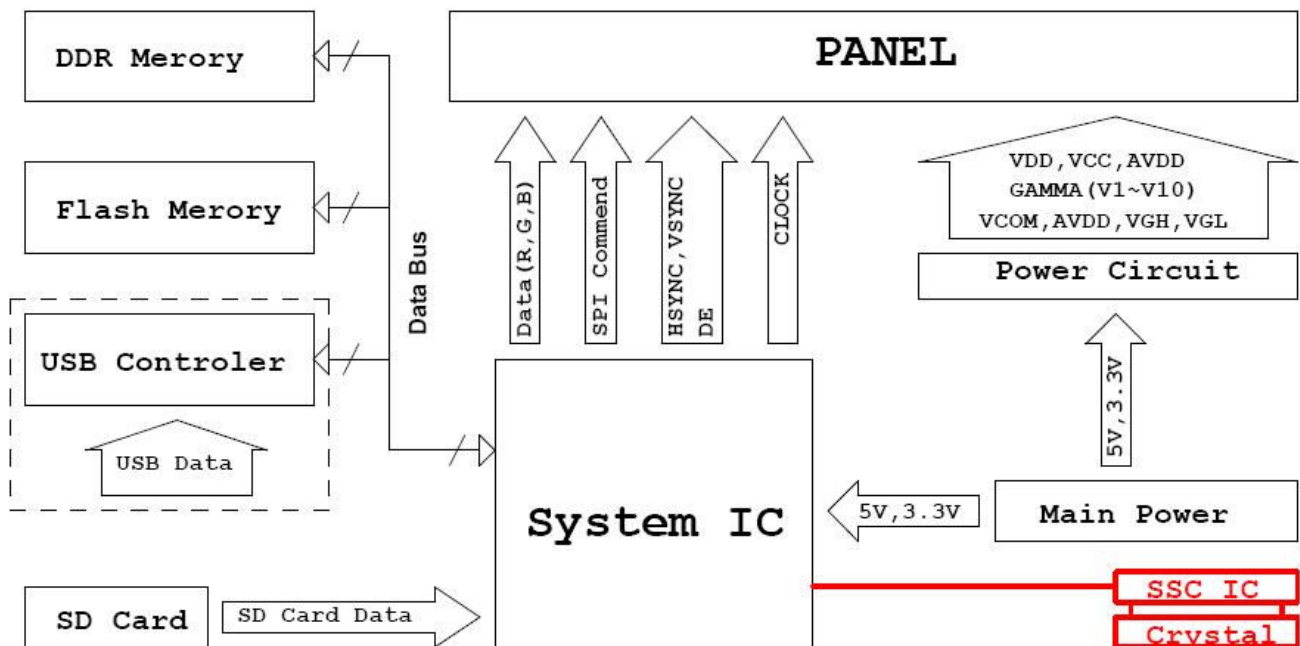
      Refer to the drawing of packing format for the location and size of the carton label.

G. Application Note
1. Application Circuit
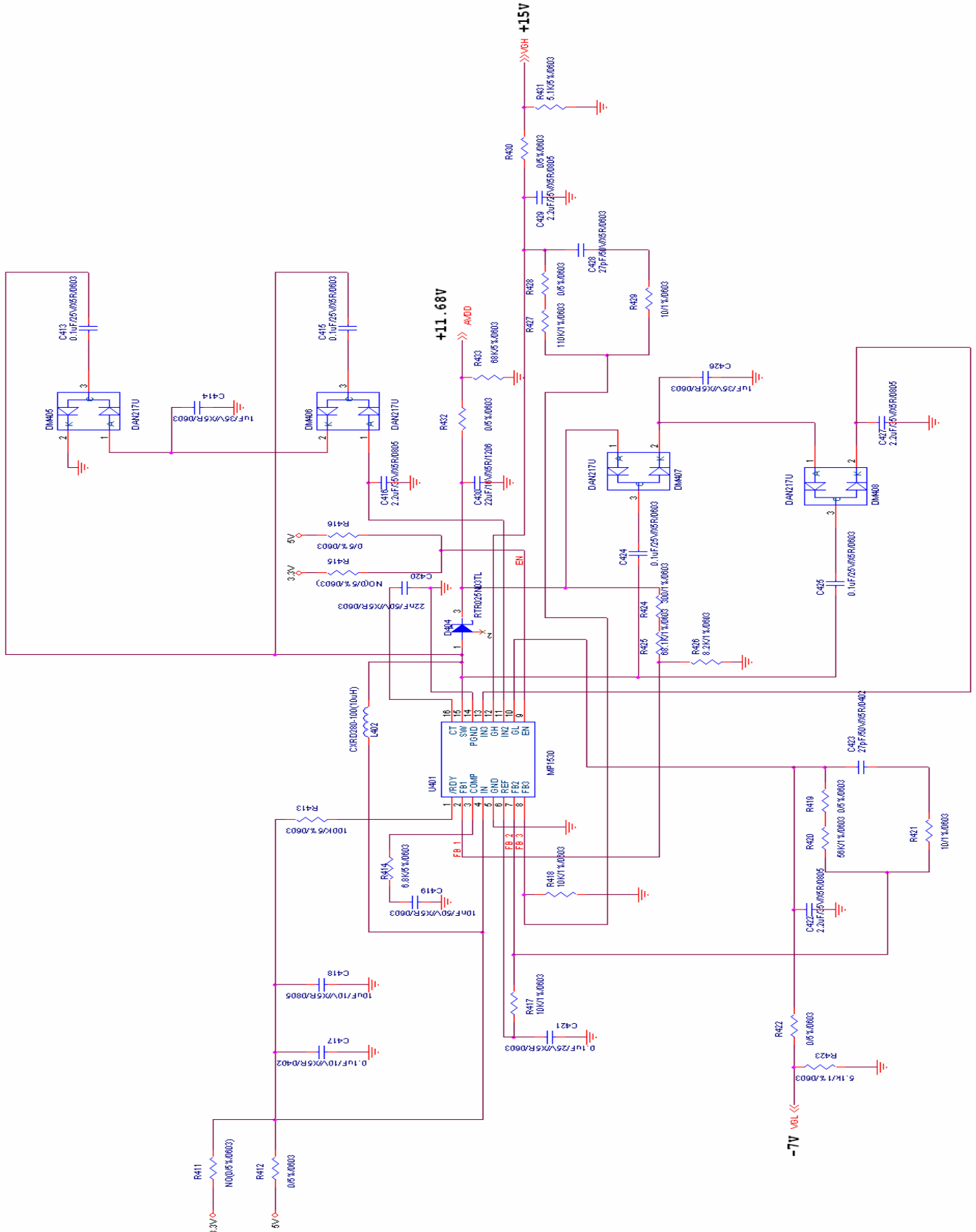
2. System block

According to there are some risks of EMI issue.
Please refer to this function block before design.
If add SSC (Spread Spectrum Clocking) IC on the clock of system may cause
USB abnormal work. Please add USB controller to control USB data.

H. Precautions

1. Do not twist or bend the module and prevent the unsuitable external force for display module during assembly.

2. Adopt measures for good heat radiation. Be sure to use the module with in the specified temperature.

3. Avoid dust or oil mist during assembly.

4. Follow the correct power sequence while operating. Do not apply the invalid signal, otherwise, it will cause improper shut down and damage the module.

5. Less EMI: it will be more safety and less noise.

6. Please operate module in suitable temperature. The response time & brightness will drift by different temperature.

7. Avoid to display the fixed pattern (exclude the white pattern) in a long period, otherwise, it will cause image sticking.

8. Be sure to turn off the power when connecting or disconnecting the circuit.

9. Polarizer scratches easily, please handle it carefully.

10. Display surface never likes dirt or stains.

11. A dewdrop may lead to destruction. Please wipe off any moisture before using module.

12. Sudden temperature changes cause condensation, and it will cause polarizer damaged.

13. High temperature and humidity may degrade performance.　Please do not expose the module to the direct sunlight and so on.

14. Acetic acid or chlorine compounds are not friends with TFT display module.

15. Static electricity will damage the module, please do not touch the module without any grounded device.

16. Do not disassemble and reassemble the module by self.

17. Be careful do not touch the rear side directly.

18. No strong vibration or shock. It will cause module broken.

19. Storage the modules in suitable environment with regular packing.

20. Be careful of injury from a broken display module.

21. Please avoid the pressure adding to the surface (front or rear side) of modules, because it will cause the display non-uniformity or other function issue.